

ABSTRACT OF THE DISCLOSURE

At least one electrode pad is formed above the surface of a semiconductor substrate. A multilevel interconnection configuration is formed between the 5 electrode pad and the semiconductor substrate. The multiple levels of interconnections in the multilevel interconnection configuration are insulated from one another by an insulating film of low dielectric constant. A dummy interconnection configuration is 10 formed at least within the insulating film around the periphery of the electrode pad.